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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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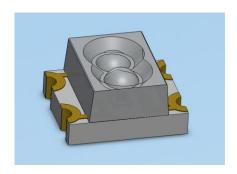






# **DATASHEET**

# SMD • B EAST3025RGA2



#### **Features**

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH
- Compliance Halogen Free .(Br <900 ppm , Cl <900 ppm , Br+Cl < 1500 ppm).

#### **Description**

- The SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

#### **Applications**

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- · General use.



# **Device Selection Guide**

Code	Chip Materials	Emitted Color	Resin Color	
R6S	AlGaInP	Brilliant Red	Water Clear	
GA	InGaN	Brilliant Green	- Water Clear	

Absolute Maximum Ratings (Ta=25℃)

Parameter Parameter	Symbol	Code	Rating	Unit	
Reverse Voltage	V <sub>R</sub>		5	V	
Forward Current	l <sub>F</sub>	R6S	50		
		GA	25	- mA	
eak Forward Current (Duty 1/10 @1KHz)	I <sub>FP</sub>	R6S	100	A	
		GA	100	− mA	
Power Dissipation	Pd	R6S	120	m.\\	
		GA	95	− mW	
Electrostatic Discharge	ESD <sub>HBM</sub>	R6S	2000	V	
Electrostatic Discharge		GA	150	– V	
Operating Temperature	$T_{opr}$		-40 ~ +85	$^{\circ}$ C	
Storage Temperature	Tstg		-40 ~ +90	$^{\circ}\! C$	
Soldering Temperature	Tsol		Reflow Soldering : 260 $^{\circ}\mathbb{C}$ for 10 sec. Hand Soldering : 350 $^{\circ}\mathbb{C}$ for 3 sec.		



**Electro-Optical Characteristics (Ta=25℃)** 

Parameter	Symbol	Code	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	R6S	450		1120	- mcd	
		GA	715		1800		_
Viewing Angle	2θ <sub>1/2</sub>			60		deg	_
Peak Wavelength	λр	R6S		632		- nm	- I <sub>F</sub> =20mA -
		GA		518			
Dominant Wavelength	λd	R6S		624		- nm	
		GA		525			
Spectrum Radiation Bandwidth	Δλ	R6S		20		- nm	
		GA		35			
Forward Voltage	V <sub>F</sub>	R6S	1.7	2.0	2.4	- V	
		GA	2.7	3.3	3.7		
Reverse Current	I <sub>R</sub>	R6S			10	– μΑ	V <sub>R</sub> =5V
		GA			50		v <sub>R</sub> =5 v

Note:

Tolerance of Luminous Intensity: ±11%



# **Bin Range of Luminous Intensity**

## R6S

Bin Code	Min.	Max.	Unit	Condition
U	450	715		
V	715	1120	mcd	$I_F = 20mA$

GA

Bin Code	Min.	Max.	Unit	Condition
V	715	1120	1	L 00 A
W	1120	1800	mcd	I <sub>F</sub> =20mA

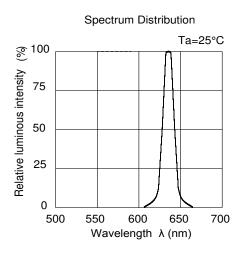
Note:

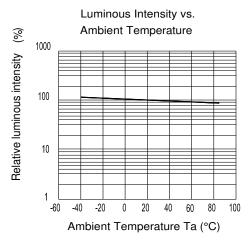
Tolerance of Luminous Intensity: ±11%

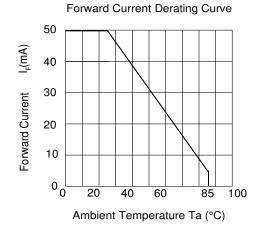


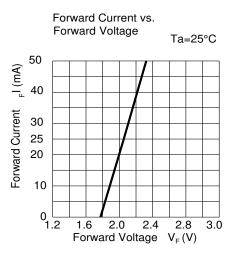
# **Typical Electro-Optical Characteristics Curves**

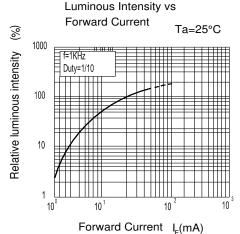
#### R6S

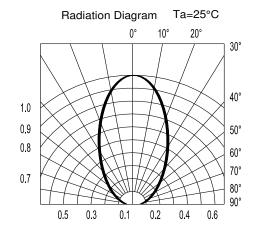










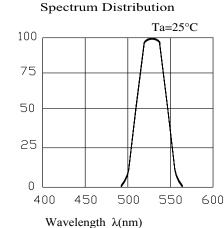




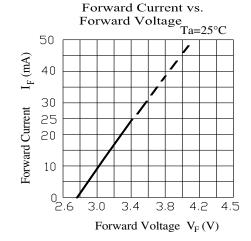
#### **Typical Electro-Optical Characteristics Curves**

#### GA

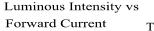


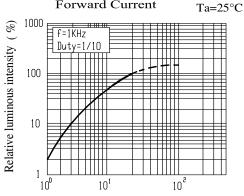


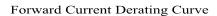
Luminous Intensity vs.



# Ambient Temperature 1000 100

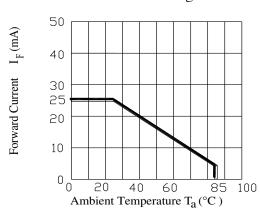






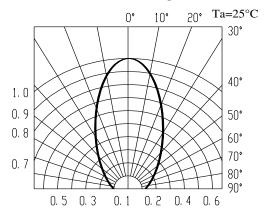
Ambient Temperature  $T_a(^{\circ}C)$ 

-20 0 20 40 60 80



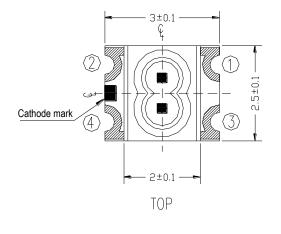
#### Radiation Diagram

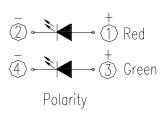
Forward Current I<sub>F</sub> (mA)

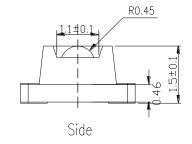




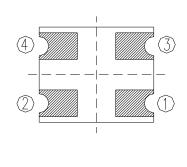
# **Package Dimension**

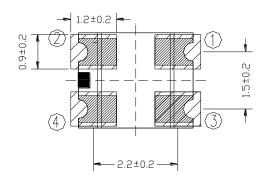












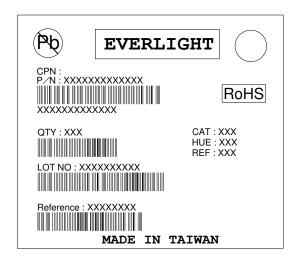
Bottom

Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

Note: Tolerances unless mentioned ±0.1 mm. Unit = mm

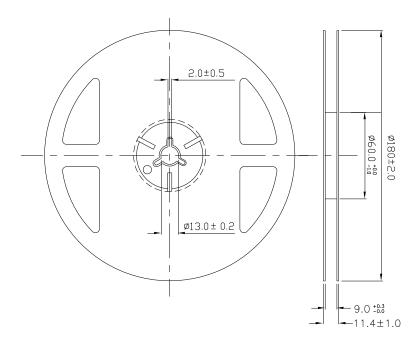


# **Label Explanation**



- · CPN: Customer's Product Number
- P/N: Product Number
- · QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Chromaticity Coordinates & Dom. Wavelength Rank
- REF: Forward Voltage Rank
- · LOT No: Lot Number

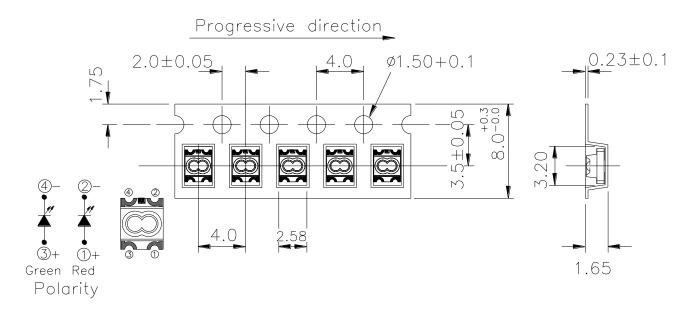
#### **Reel Dimensions**



Note: The tolerances unless mentioned is  $\pm 0.1 \text{mm}$ , Unit = mm

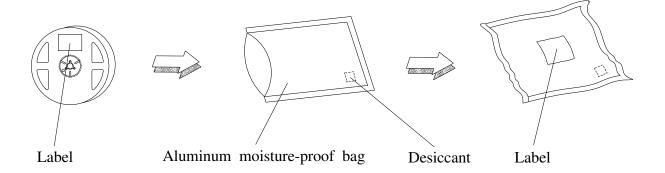


# Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel



Note: The tolerances unless mentioned is  $\pm 0.1$ mm ,Unit = mm

## **Moisture Resistant Packaging**





#### **Precautions For Use**

#### 1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change ( Burn out will happen ).

#### 2. Storage

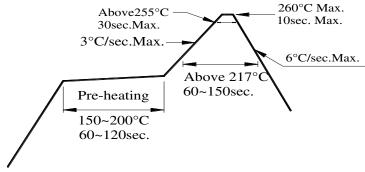
- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 1 year under 30℃ or less and 60% RH or less.

If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment:  $60\pm5^{\circ}$ C for 24 hours.

#### 3. Soldering Condition

3.1 Pb-free solder temperature profile



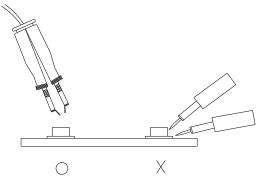
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

#### 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than  $350^{\circ}$ C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

#### 5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



DATASHEET SMD • B EAST3025RGA2



# **Application Restrictions**

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlightamericas before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.